

Product Information Sheet

MATERIAL ID: EPO-TEK® OG147-7

Date: 08/2007 **Per:**

Rev: II

Material Description: A single component, thixotropic, UV curable epoxy, designed for

adhesive, sealing, and encapsulating applications found in

semiconductor, electro-optics, fiber optics, medical, and scientific / OEM industries. It is a high viscosity epoxy ideal for COB glob top

"dam" encapsulation processes.

Number of Components: Single **Mix Ratio by weight:** N/A

Cure Schedule (minimum)* $100 \text{mW/cm}^2 \text{ for } > 3 \text{ minutes } @ 320-500 \text{ nm (depending on thickness)}$

Specific Gravity: 1.07 --- Part A: Part B:

Pot Life: N/A

Shelf Life: One year at room temperature

NOTE: Container(s) should be kept closed in a dark location when not in use.

*Please see Applications Note(s) available on our website.

MATERIAL CHARACTERISTICS: To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.

^{*} denotes test on lot acceptance basis; Cure condition: varies as required

PHYSICAL PROPERTIES:				
*Color (before cure):	Cloudy White	Die Shear @ 23°C:	\geq 20 Kg / 6,800 psi	
*Consistency:	Smooth thixotropic paste	Degradation Temp:	414 ° C	
*Viscosity (23°C):		Weight Loss:		
@ 10 rpm	30,000 - 40,000 cPs	@ 200°C:	0.09 %	
Thixotropic Index:	2.1	@ 250°C:	0.29 %	
*Glass Transition	\geq 70 ° C (Post-Cure	@ 300°C:	0.80 %	
Dynamic Scan 20—200°C; R	amp -10—200°C @ 20°C/Min)	Operating Temp:		
Coefficient of Thermal Expansion (CTE):		Continuous:	- 55° C to + 200° C	
Below Tg:	45 x 10 ⁻⁶ in/in°C	Intermittent:	- 55° C to + 300° C	
Above Tg:	190 x 10⁻⁶ in/in°C	Storage Modulus @ 23°C: 269,396 psi		
Shore D Hardness:	81	*Particle Size:	≤ 20 microns	

OPTICAL PROPERTIES @ 23°C:				
Spectral Transmission:	>83 % @ 800-2000 nm	Index of Refraction:	1.5690 @ 589 nm	
	>78 % @ 580-800 nm			
	>56 % @ 400-580 nm			